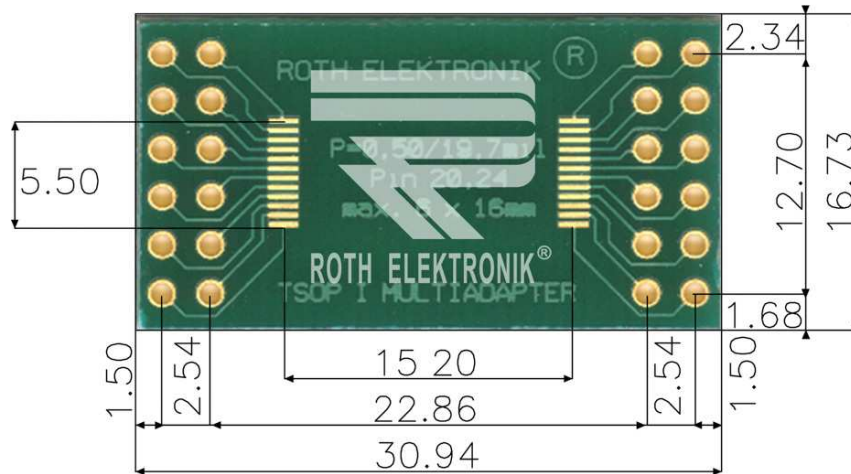




RE900-03

- Epoxy fibre-glass FR4 1.50 mm
 - Double-sided 35 µm Cu
 - Plated through holes (PTH)
 - Surface chem. Ni/Au with solder stop mask
 - Adaption circuit board for TSOP I 20, 24 (0.50 mm)
 - Hole diameter 1.00 mm
 - Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
 - Size 16.73 x 30.94 mm
- Module-No. Type Pitch Pin Size (mm)

RE900-03 TSOP I 0.500 mm 20, 24 6.00 x 16.00